

## Introduction to Digital Signal Processing Systems



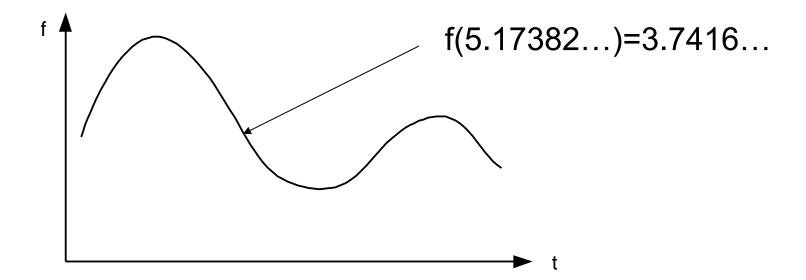
### Outline

- Introduction
- Typical DSP algorithms
- Scaled CMOS technologies
- Representations of DSP algorithms



### Analog Signal

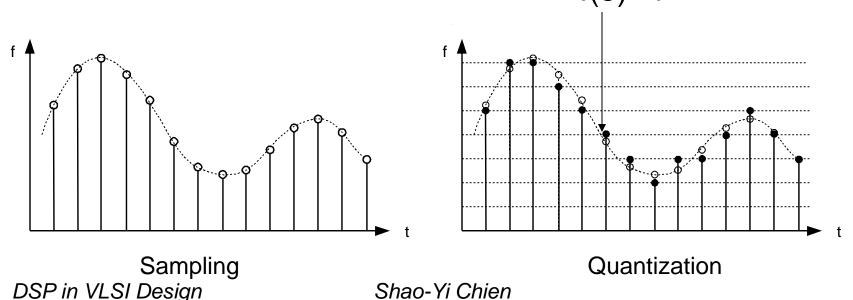
- Real-word signal
- Infinite accuracy on time and magnitude





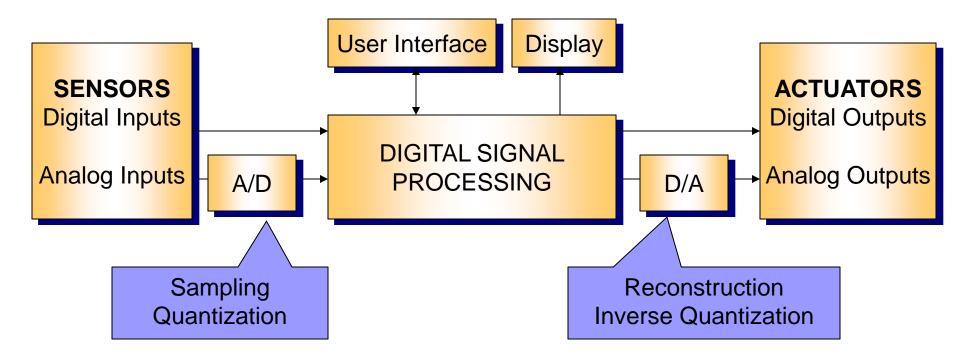
## **Digital Signal**

- Get after sampling and quantization
- Finite accuracy on time and magnitude
- Easy to process with digital processing element f(5)=4





## **Typical DSP Systems**





## Advantages of Analog Signal Processing

- Can operate in very high frequency
- Sometimes low area
- Low power



## Advantages of Digital Signal Processing (DSP)

#### More robust

- □ Insensitive to environment and component tolerance
- The accuracy can be controlled better
- Can cancel the noise and interference while amplifying the signal
- Predictable, repeatable behavior
  - Can be stored and recovered, transmitted and received, processed and manipulated without error



### Features of DSP Systems

- Real-time throughput requirement
   So-called hard real-time systems
- Data-driven property
- Non-terminating program



#### Hard Real-Time Systems



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#### "Real-time Computing" for Formula 1



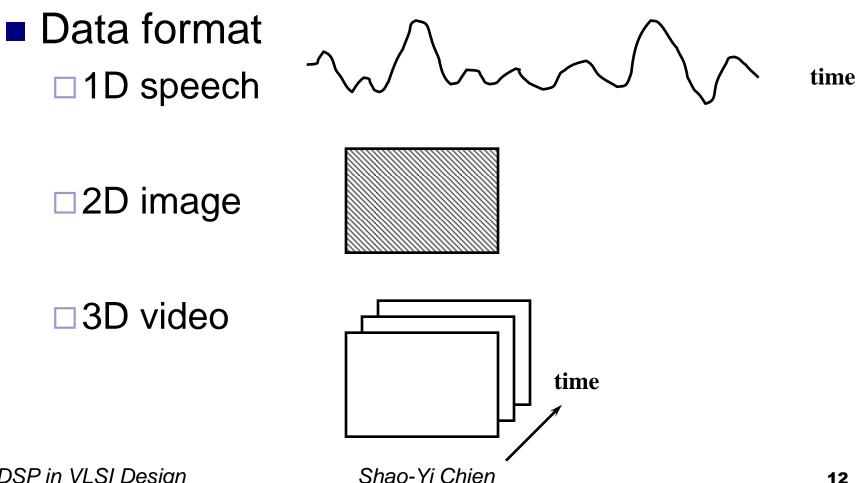


## Performance Metrics of DSP Systems

- Hardware circuitry and resources (area)
- Speed of execution
- Power consumption
- Finite word length performance



#### **Characteristics of DSP Systems** (1/4)



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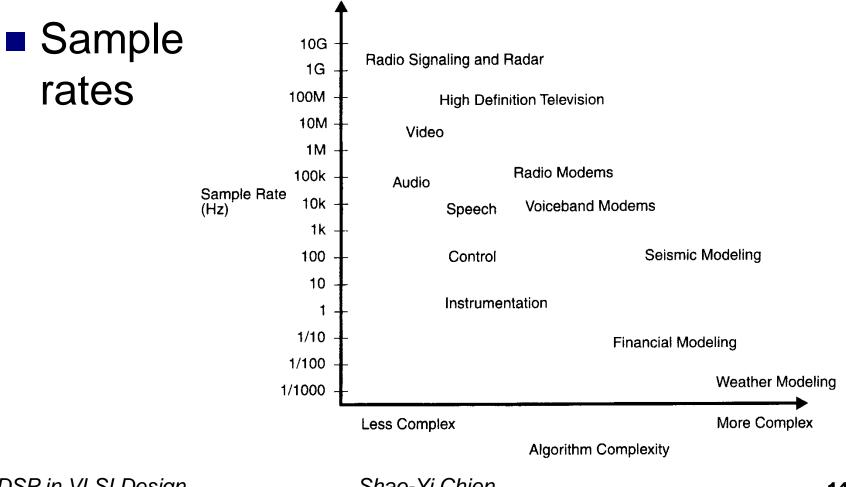
## Characteristics of DSP Systems (2/4)

Algorithms

| DSP Algorithm                          | System Application  |
|--|---|
| Speech coding and decoding             | Digital cellular telephones, personal communications systems, digital cordless telephones, multimedia computers, secure communications  |
| Speech encryption and decryption       | Digital cellular telephones, personal communications systems, digital cordless telephones, secure communications  |
| Speech recognition                     | Advanced user interfaces, multimedia workstations, robotics, automotive<br>applications, digital cellular telephones, personal communications systems, digital<br>cordless telephones   |
| Speech synthesis                       | Multimedia PCs, advanced user interfaces, robotics  |
| Speaker identification                 | Security, multimedia workstations, advanced user interfaces   |
| Hi-fi audio encoding<br>and decoding   | Consumer audio, consumer video, digital audio broadcast, professional audio,<br>multimedia computers  |
| Modem algorithms                       | Digital cellular telephones, personal communications systems, digital cordless<br>telephones, digital audio broadcast, digital signaling on cable TV, multimedia comput-<br>ers, wireless computing, navigation, data/facsimile modems, secure communications |
| Noise cancellation                     | Professional audio, advanced vehicular audio, industrial applications   |
| Audio equalization                     | Consumer audio, professional audio, advanced vehicular audio, music   |
| Ambient acoustics<br>emulation         | Consumer audio, professional audio, advanced vehicular audio, music   |
| Audio mixing and editing               | Professional audio, music, multimedia computers   |
| Sound synthesis                        | Professional audio, music, multimedia computers, advanced user interfaces   |
| Vision                                 | Security, multimedia computers, advanced user interfaces, instrumentation, robotics, navigation   |
| Image compression<br>and decompression | Digital photography, digital video, multimedia computers, video-over-voice, consumer video  |
| Image compositing                      | Multimedia computers, consumer video, advanced user interfaces, navigation  |
| Beamforming                            | Navigation, medial imaging, radar/sonar, signals intelligence   |
| Echo cancellation                      | Speakerphones, modems, telephone switches   |
| Spectral estimation                    | Signals intelligence, radar/sonar, professional audio, music  |



## **Characteristics of DSP Systems** (3/4)



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# Characteristics of DSP Systems (4/4)

- Clock rates
- Numeric representations



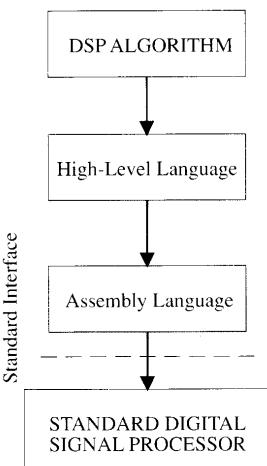
# Standard Digital Signal Processors (1/2)

- Allow rapid prototyping and time-to-market
- Sometimes, the execution speed and code size is reasonably good
- Not always cost effective
- Often cannot meet the requirements of throughput, power consumption, and size



# Standard Digital Signal Processors (2/2)

- DSP Architectures
   Harvard architecture
   MAC
  - □ Fixed-point arithmetic



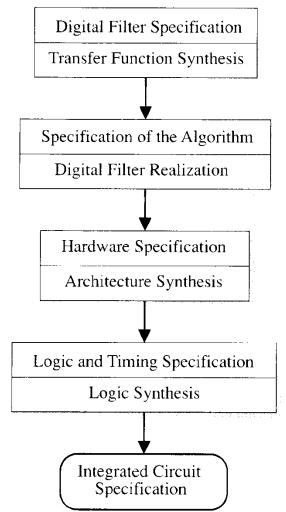
# Application-Specific ICs for DŠP (1/2)

Better performances
 Processing capacity
 Power consumption
 Pin-restriction problem
 Main problem is the system is very complex to design

Long time-to-market

## Application-Specific ICs for DSP (2/2)

- Large design space
- Hard to find optimal solution
- System → specification → algorithm → hardware architecture → logic implementation → VLSI implementation





## **Typical DSP Algorithms**

- Convolution
- Correlation
- Digital filters
- Adaptive filters
- Motion estimation
- Discrete cosine transform (DCT)
- Vector quantization (VQ)
- Viterbi algorithm and dynamic programming
- Decimator and expander
- Wavelets and filter banks

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## Convolution (1/2)

$$y(n) = x(n) * h(n) = \sum_{k=-\infty}^{\infty} x(k)h(n-k).$$

Can be used to describe the behavior of a linear time-invariant systems

 x(n): input signal
 y(n): output signal
 h(n): unit-sample response



## Convolution (2/2)

- Finite impulse response (FIR) system  $h(n) = \frac{1}{M_1 + M_2 + 1} \sum_{-M_1}^{M_2} \delta(n - k)$
- Infinite impulse response (IIR) system

$$h(n) = \sum_{k=-\infty}^{n} \delta(k)$$



### **Digital Filters**

• LTI, causal filter  $y(n) = -\sum_{k=1}^{N} a_k y(n-k) + \sum_{k=0}^{M-1} b_k x(n-k).$ 

M-tap finite impulse response filter

$$y(n) = \sum_{k=0}^{M-1} b_k x(n-k)$$

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#### **Chip Development**

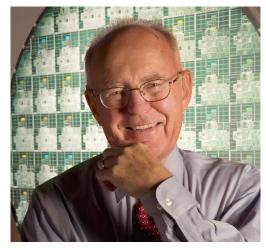
10 miljarder ANTAL TRANSISTORER 1 miljard Pentium II Pentium Pro NOOre'S IAW 100 miljoner 10 miljoner Pentium 1 miljon 386 100 tusen 80286 10 tusen 18085 ÅR 8080  $\bar{0}04$ 1 tusen 1971 1976 1981 1986 1991 1996 2001

#### <u>Technology roadmap:</u>

http://notes.sematech.org/ntrs/PubINTRS.nsf

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<u>Moore's law:</u> The number of transistors per chip doubles every 18 months.

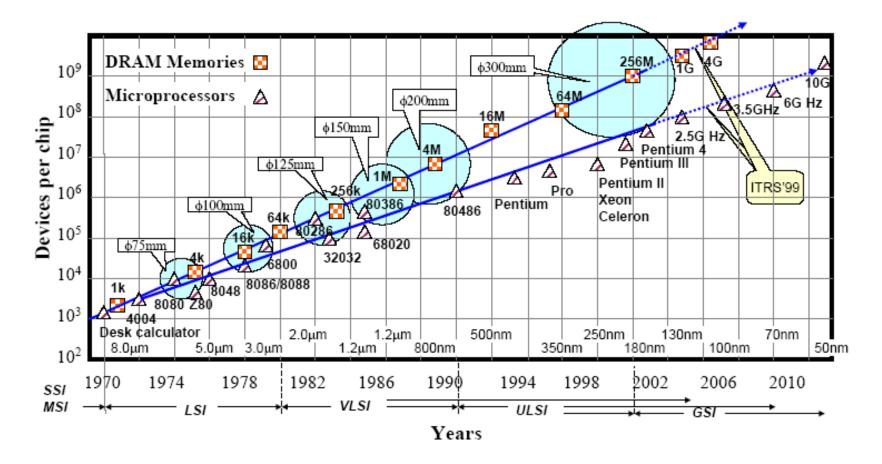


Gordon Moore One of the founders of Intel

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#### Moore's Law



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# Scaled CMOS technology (Moore's Law) (1/3)

| Year of Production:                | 2001    | 2003    | 2005    | 2007               | 2010    | 2016    |
|------------------------------------|---------|---------|---------|--------------------|---------|---------|
| DRAM Half-Pitch [nm]:              | 130     | 100     | 80      | 65                 | 45      | 22      |
| Overlay Accuracy [nm]:             | 46      | 35      | 28      | 23                 | 18      | 9       |
| MPU Gate Length [nm]:              | 90      | 65      | 45      | 35                 | 25      | 13      |
| CD Control [nm]:                   | 8       | 5.5     | 3.9     | 3.1                | 2.2     | 1.1     |
| T <sub>ox</sub> (equivalent) [nm]: | 1.3-1.6 | 1.1-1.6 | 0.8-1.3 | 0.6-1.1            | 0.5-0.8 | 0.4-0.5 |
| Junction Depth [nm]:               | 48-95   | 33-66   | 24-47   | <mark>18-37</mark> | 13-26   | 7-13    |
| Metal Cladding [nm]:               | 16      | 12      | 9       | 7                  | 5       | 2.5     |
| Inter-Metal Dielectric K:          | 3.0-3.6 | 3.0-3.6 | 2.6-3.1 | 2.3-2.7            | 2.1     | 1.8     |

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## Scaled CMOS technology (Moore's Law) (2/3)

| Year of first DRAM shipment                                    | 1995 | 1998 | 2001 | 2004 | 2007  | 2010  |
|--|------|------|------|------|-------|-------|
| Minimum feature of size (um)                                   | 0.35 | 0.25 | 0.18 | 0.13 | 0.10  | 0.07  |
| Memory in bits/chip<br>(DRAM/FLASH)                            | 64M  | 256M | 1G   | 4G   | 16G   | 64G   |
| Microprocessor transistor per chip ( 2.3 times per generation) | 12M  | 28M  | 64M  | 150M | 350M  | 800M  |
| ASIC (gate per chip)   | 5M   | 14M  | 26M  | 50M  | 210M  | 430M  |
| Chip frequency (MHz) for a<br>high-performance on-chip clock   | 300  | 450  | 600  | 800  | 1,000 | 1,100 |
| Maximum number of wiring levels (logic), on chip               | 4-5  | 5    | 5-6  | 6    | 6-7   | 7-8   |
| Power supply voltage (V) for desktop                           | 3.3  | 2.5  | 1.8  | 1.5  | 1.2   | 0.9   |
| Maximum power for high<br>performance with heat sink (W)       | 80   | 100  | 120  | 140  | 160   | 180   |

Source: SIA (Semiconductor Industry Association) road map ITRS: International Technology Roadmap for Semiconductors http://www.itrs.net/

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# Scaled CMOS technology (Moore's Law) (3/3)

| Year of Production  | 2013            | 2015           | 2017              | 2019                      | 2021                      | 2023              | 2025     | 2028              |
|---|-----------------|----------------|-------------------|---------------------------|---------------------------|-------------------|----------|-------------------|
| Logic Industry "Node Name" Label                                      | "16/14"         | "10"           | "7"               | "5"                       | "3.5"                     | "2.5"             | "1.8"    |                   |
| Logic ½ Pitch (nm)  | 40              | 32             | 25                | 20                        | 16                        | 13                | 10       | 7                 |
| Flash ½ Pitch [2D] (nm)   | 18              | 15             | 13                | 11                        | 9                         | 8                 | 8        | 8                 |
| DRAM ½ Pitch (nm)   | 28              | 24             | 20                | 17                        | 14                        | 12                | 10       | 7.7               |
| FinFET Fin Half-pitch (new) (nm)                                      | 30              | 24             | 19                | 15                        | 12                        | 9.5               | 7.5      | 5.3               |
| FinFET Fin Width (new) (nm)   | 7.6             | 7.2            | <mark>6.</mark> 8 | 6.4                       | 6.1                       | 5.7               | 5.4      | 5.0               |
| 6-t SRAM Cell Size(um2) [@60f2]                                       | 0.096           | 0.061          | 0.038             | 0.024                     | 0.015                     | 0.010             | 0.0060   | 0.0030            |
| MPU/ASIC HighPerf 4t NAND Gate Size(um2)                              | 0.248           | 0.157          | 0.099             | 0.062                     | 0.039                     | 0.025             | 0.018    | 0.009             |
| 4-input NAND Gate Density (Kgates/mm) [@155f2]                        | 4.03E+03        | 6.37E+03       | 1.01 <b>E+</b> 04 | 1.61 <b>E+</b> 04         | 2.55 <b>E+</b> 04         | 4.05 <b>E+</b> 04 | 6.42E+04 | 1.28 <b>E+</b> 05 |
| Flash Generations Label (bits per chip) (SLC/MLC)                     | 64G /128G       | 128G /256G     | 256G / 512G       | 512 <b>G</b> / 1 <b>T</b> | 512 <b>G</b> / 1 <b>T</b> | 1T / 2T           | 2T / 4T  | 4T / 8T           |
| Flash 3D Number of Layer targets (at relaxed Poly half pitch)         | 16-32           | 16-32          | 16-32             | 32-64                     | 48-96                     | 64-128            | 96-192   | 192-384           |
| Flash 3D Layer half-pitch targets (nm)                                | 64nm            | 54nm           | 45nm              | 30nm                      | 28nm                      | 27nm              | 25nm     | 22nm              |
| DRAM Generations Label (bits per chip)                                | 4G              | 8G             | 8 <b>G</b>        | 16 <b>G</b>               | 32G                       | 32G               | 32G      | 32G               |
| 450mm Production High Volume Manufacturing Begins (100Kwspm)          |                 |                |                   | 2018                      |                           |                   |          |                   |
| Vdd (High Performance, high Vdd transistors)[**]                      | 0.86            | 0.83           | 0.80              | 0.77                      | 0.74                      | 0.71              | 0.68     | 0.64              |
| 1/(CV/I) (1/psec) [**]  | 1.13            | 1.53           | 1.75              | 1.97                      | 2.10                      | 2.29              | 2.52     | 3.17              |
| On-chip local clock MPU HP [at 4% CAGR]                               | 5.50            | 5.95           | 6.44              | 6.96                      | 7.53                      | 8.14              | 8.8      | 9.9               |
| Maximum number wiring levels [unchanged                               | 13              | 13             | 14                | 14                        | 15                        | 15                | 16       | 17                |
| MPUHigh-Performance (HP) Printed Gate Length (GLpr) (nm) [**]         | 28              | 22             | 18                | 14                        | 11                        | 9                 | 7        | 5                 |
| MPU High-Performance Physical Gate Length (GLph) (nm) [**]            | 20              | 17             | 14                | 12                        | 10                        | 8                 | 7        | 5                 |
| ASIC/Low Standby Power (LP) Physical Gate Length (nm) (GLph)[**]      | 23              | 19             | 16                | 13                        | 11                        | 9                 | 8        | 6                 |
| ** Note: from the PIDS working group data; however, the calibration o | of Vdd, GLph, a | nd I/CV is ong | oing for improv   | ed targets in 2           | 014 ITRS work             | ļ                 |          |                   |

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## DSP and VLSI

#### Modern DSP

□ Well suite to VLSI implementation

Feasible or economically viable only if implemented using VLSI technologies

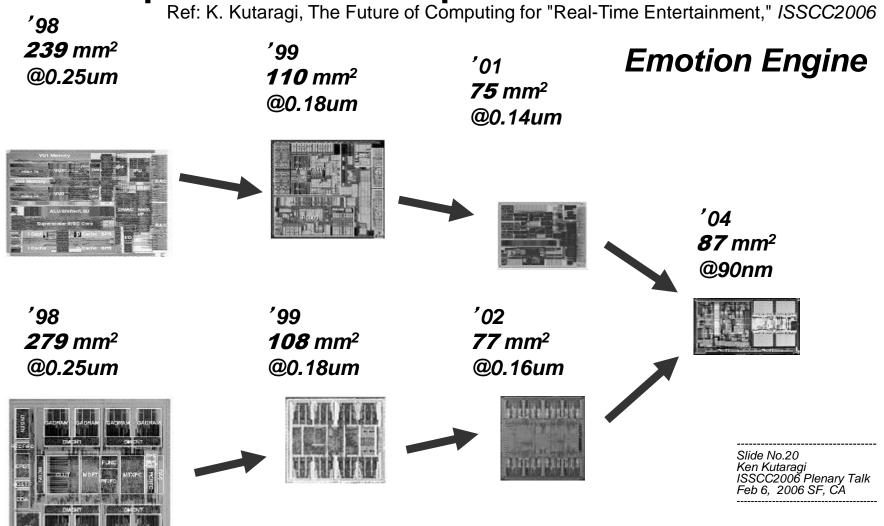
#### VLSI

□ Large investment → need large volume of products

- Communication
- Consumer applications
- Necessary performance requirement (especially realtime requirement)
  - DSP systems are hard real-time systems



#### Example: the Chip for PS2



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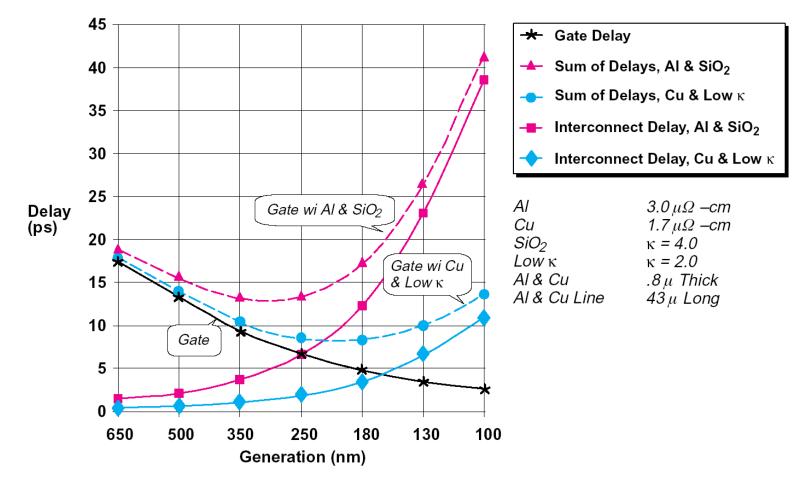
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30

**Graphics Synthesizer** 



#### **Problems: Interconnection**



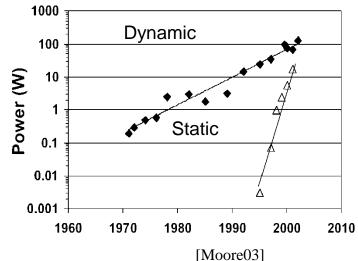
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#### **Problems: Increasing Static Power**

#### V<sub>DD</sub> decreases

- □ Save dynamic power
- Protect thin gate oxides and short channels
- No point in high value because of velocity sat.
- V<sub>t</sub> must decrease to maintain device performance
- But this causes exponential increase in OFF leakage
- Major future challenge



8,000 7.000 6,000 5,000 Power [mW] 4,000 3,000 2,000 1,000 0 2014 2015 2016 2017 2018 2019 2020 2009 2010 2011 2012 2013 2021 2022 2023 2024 Irend: Logic Static Power ITTEND: Memory Static Power Image: Memory Dynamic Power Trend: Logic Dynamic Power -----Requirement: Dynamic plus Static Power

Figure SYSD6 SOC Consumer Portable Power Consumption Trends—UPDATED

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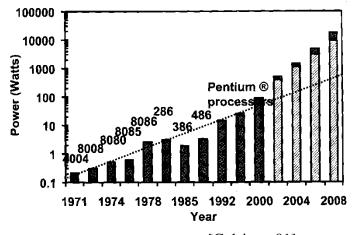


### Problems: Power Density

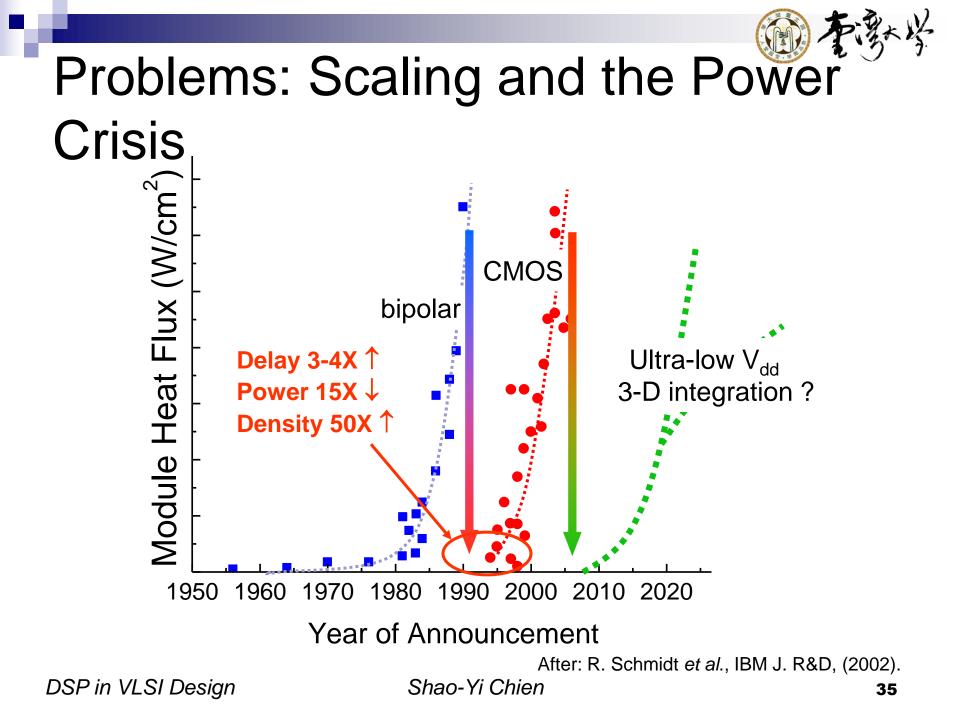
- Intel VP Patrick Gelsinger (ISSCC 2001)
  - If scaling continues at present pace, by 2005, high speed processors would have power density of nuclear reactor, by 2010, a rocket nozzle, and by 2015, surface of sun.

"Business as usual will not work in the future."

- Intel stock dropped 8% on the next day
- But attention to power is increasing



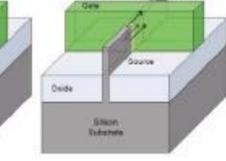
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#### FinFET





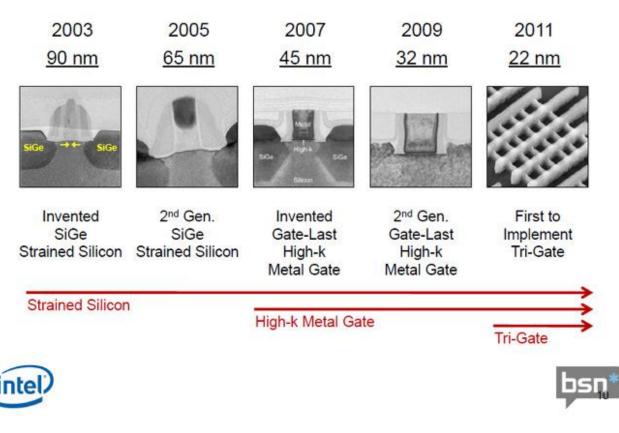
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#### FinFET

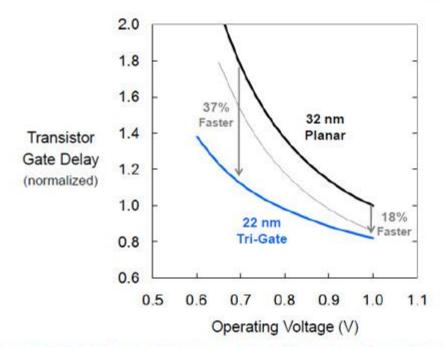
#### Intel Transistor Leadership





#### FinFET



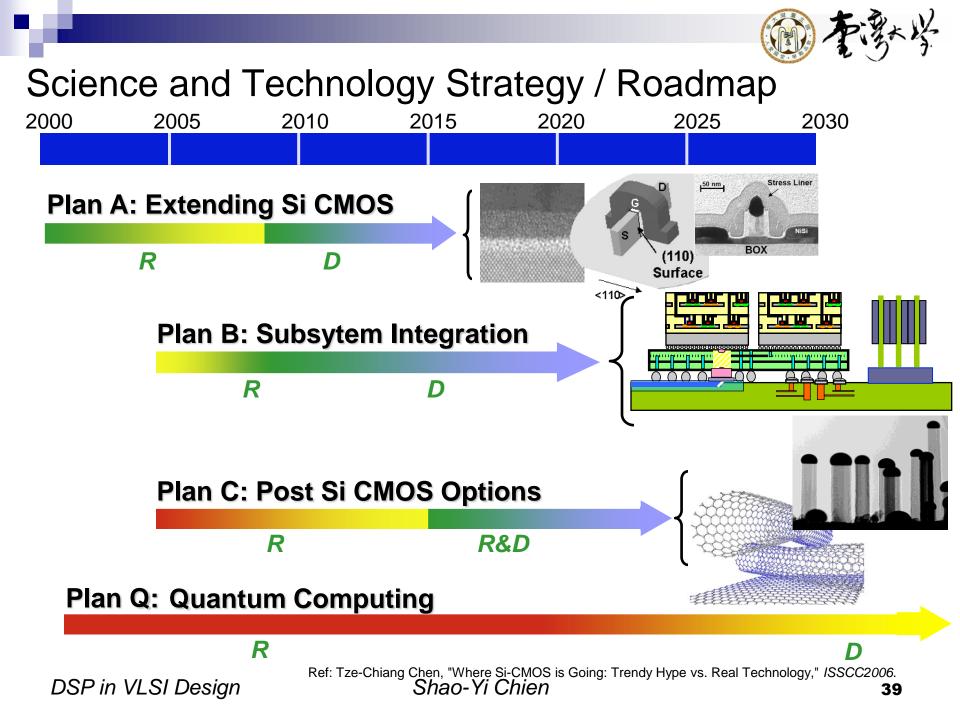


22 nm Tri-Gate transistors provide improved performance at high voltage and an *unprecedented* performance gain at low voltage



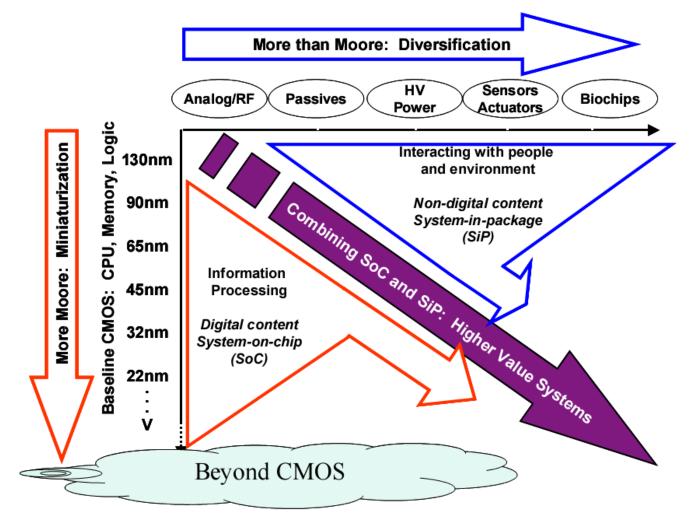
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#### More Moore & More than Moore !!!

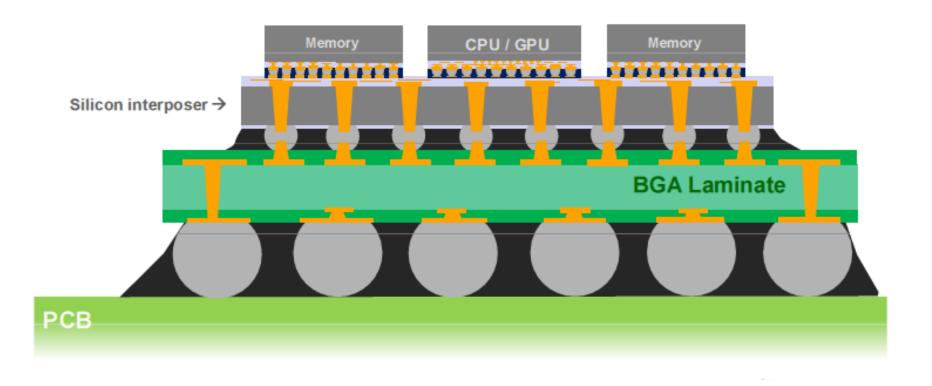


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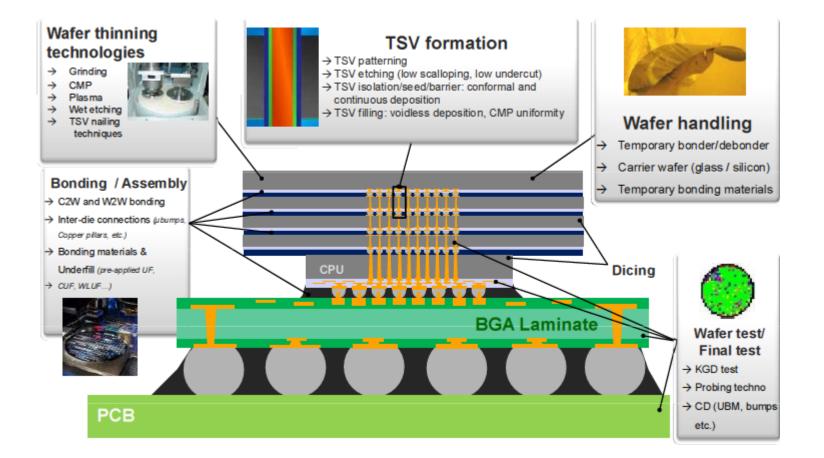


#### 2.5D Interposer





#### 3D-IC Technology





#### DSP Architecture Design?

- Given DSP algorithms, find the "best" solution in the design space under certain constraints
- Or, modified or develop the algorithm to be "hardware oriented" or "hardware friendly," and then develop the hardware architecture

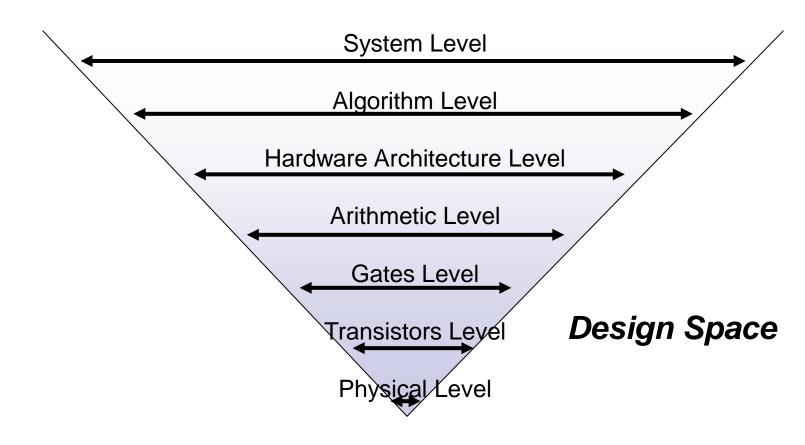


#### **Abstraction Layers**

- System (ex: MP3 player)
- Algorithm (ex: FIR filter)
- Hardware architecture (ex: array architecture,...)
- Arithmetic units (ex: multiplier, adder, ...)
- Logic gates (ex: AND, OR, ...)
- Transistors (ex: NMOS, PMOS)
- Layout

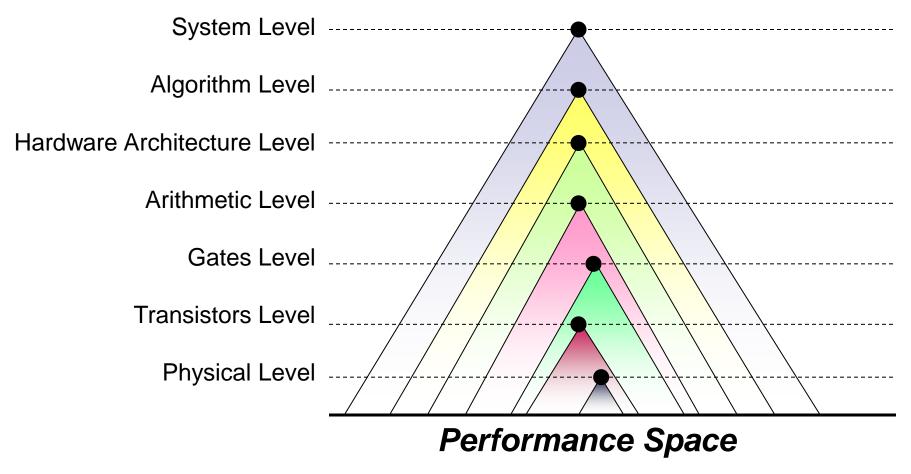


#### The Higher the Abstraction, The Larger Design Space





#### The Higher the Abstraction, The More Important



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## Representations of DSP Algorithms

- DSP algorithms: nonterminating program y(n) = ax(n) + bx(n-1) + cx(n-2) for n = 1 to  $n = \infty$ .
- Iteration period
- Sampling rate
- Latency
- Throughput
- Clock frequency
- Critical path



## Graphical Representations of DSP Algorithms

- Can bridge the gap between algorithmic descriptions and structural implementations
- Block diagram
- Signal-flow graph (SFG)
- Data-flow graph (DFG)
- Dependence graph (DG)



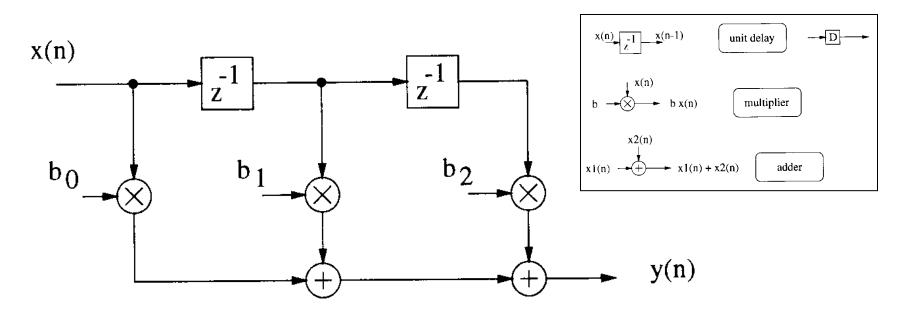
## Block Diagram (1/5)

- The most frequently used representation
- Can be constructed with different levels of abstraction
- Can be directly mapped to circuits implementation



### Block Diagram (2/5)

 $y(n) = b_0 x(n) + b_1 x(n-1) + b_2 x(n-2)$ 



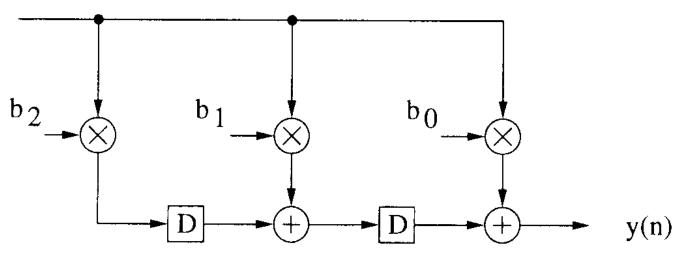


### Block Diagram (3/5)

#### Data broadcast FIR filter

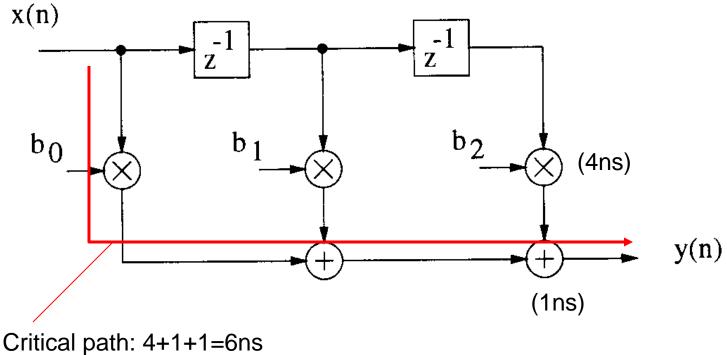
 $\mathbf{x}(\mathbf{n})$ 

I





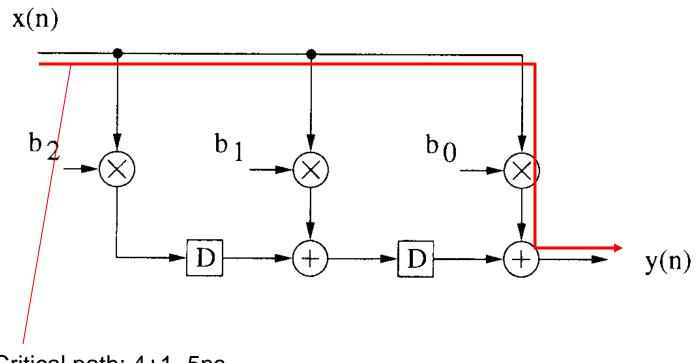
#### Block Diagram (4/5)



Max clock frequency = 1s/6ns=167MHz



## Block Diagram (5/5)



Critical path: 4+1=5ns Max clock frequency = 1s/5ns=200MHz

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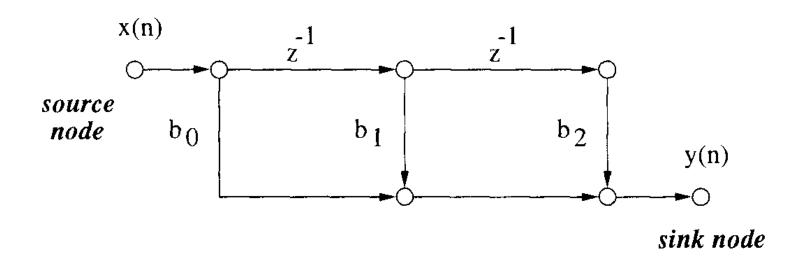


## Signal Flow Graph (SFG) (1/4)

Nodes k
Computation or task
Directed edges (j, k)
Linear transformation
Source node
Sink node



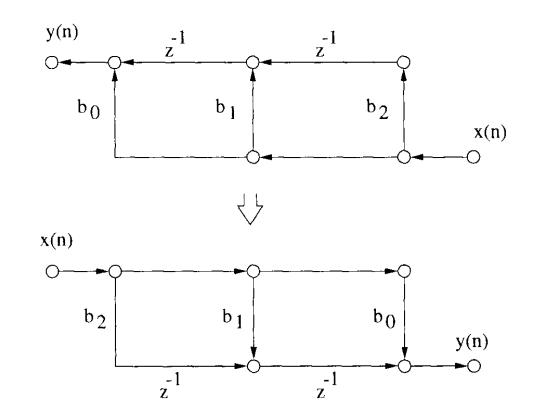
### Signal Flow Graph (SFG) (2/4)





### Signal Flow Graph (SFG) (3/4)

Transpose property





# Signal Flow Graph (SFG) (4/4)

- Used in digital filter structure and analysis of finite word-length effects
- Only applicable to linear networks
- Cannot be used to describe multi-rate DSP systems



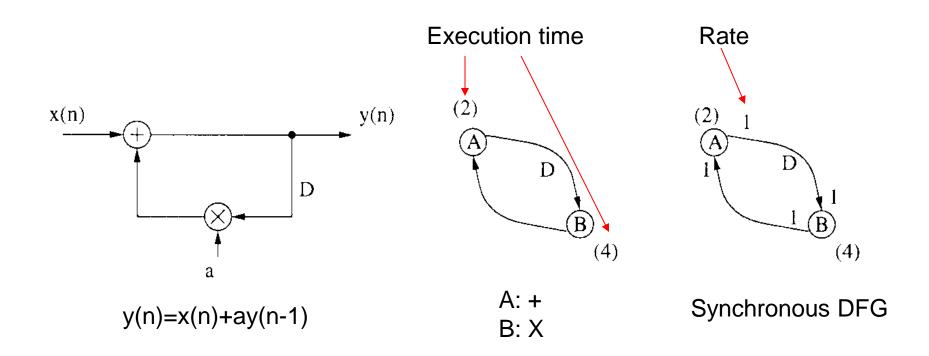
## Data-Flow Graph (DFG) (1/4)

#### Nodes

- Computations
- Directed edges
  - □ Data paths (communication)
  - □ Has a nonnegative number of delays



#### Data-Flow Graph (DFG) (2/4)





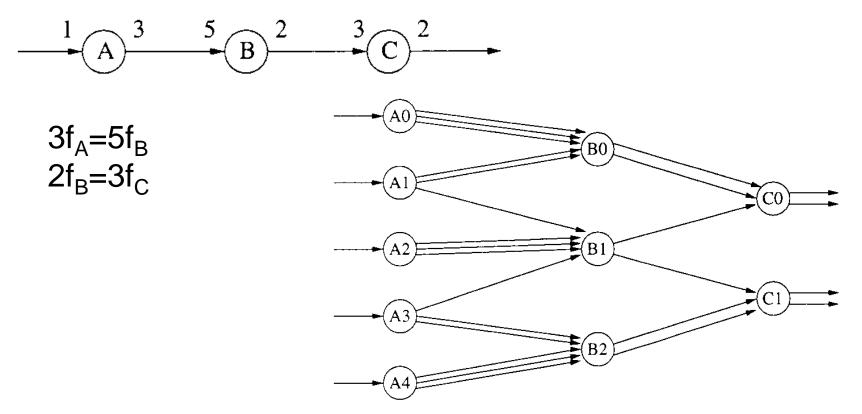
## Data-Flow Graph (DFG) (3/4)

- Data-driven property of DSP
  - Any node can fire whenever all the input data are available
  - □ Intra-iteration precedence constraint
  - □ Inter-iteration precedence constraint
- Can be used to describe both linear single-rate and nonlinear multi-rate DSP systems



### Data-Flow Graph (DFG) (4/4)

 Use single rate DFG (SRDFG) to represent multi-rate DFG (MRDFG)



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## Dependence Graph (1/2)

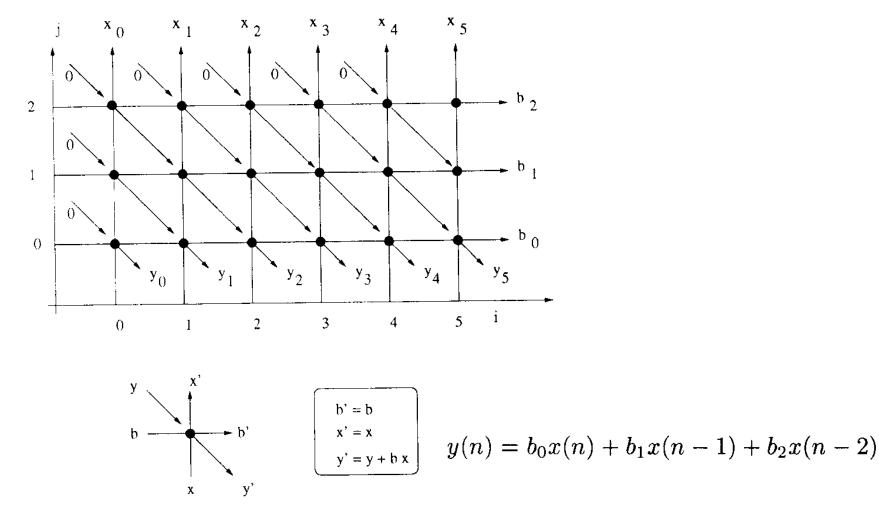
- A directed graph that shows the dependence of the computation
- Node: computation
- No node in a DG is ever reused on a single computation basis

□ Single-assignment representation

Used for systolic-array design



#### Dependence Graph (2/2)



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63



## DFG v.s. DG

#### DFG

- Nodes only cover computation in one iteration, and will be reused iteratively
- Contain delay elements

#### DG

- Contains computation for all iterations, and is used only once
- No delay elements contained